

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0736590001](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 12 Circuits, Gold (Au) 0.76µm (30µ")

Documents:

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

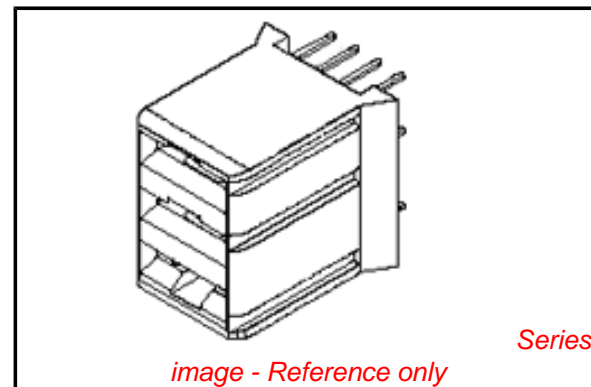
CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series [73659](#)
 Application Backplane
 Comments Midplane Power Module
 Component Type Power Header
 Overview [hdm](#)
 Product Name HDM®
 Style N/A

Physical

Circuits (Loaded) 12
 Circuits (maximum) 12
 Color - Resin Black
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part No
 Keying to Mating Part None
 Material - Metal Beryllium Copper
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 Number of Columns 1
 Number of Pairs Open Pin Field
 Number of Rows 3
 Orientation Vertical
 PC Tail Length (in) 0.079 In
 PC Tail Length (mm) 2.00 mm
 PCB Locator No
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.098 In
 PCB Thickness Recommended (mm) 2.50 mm
 Packaging Type Tube
 Pitch - Mating Interface (in) 0.079 In
 Pitch - Mating Interface (mm) 2.00 mm
 Pitch - Term. Interface (in) 0.079 In
 Pitch - Term. Interface (mm) 2.00 mm
 Plating min: Mating (µin) 30
 Plating min: Mating (µm) 0.75
 Plating min: Termination (µin) 150
 Plating min: Termination (µm) 3.75



EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Not Reviewed**
**Halogen-Free
 Status
 Not Reviewed**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73659Series](#)

Mates With

[73651](#) HDM® Board-to-Board
 Daughterboard Power Module

Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	15A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	38
Shielded	Yes
Voltage - Maximum	500V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0819
Sales Drawing	SDA-73659-000*

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This document was generated on 05/14/2010

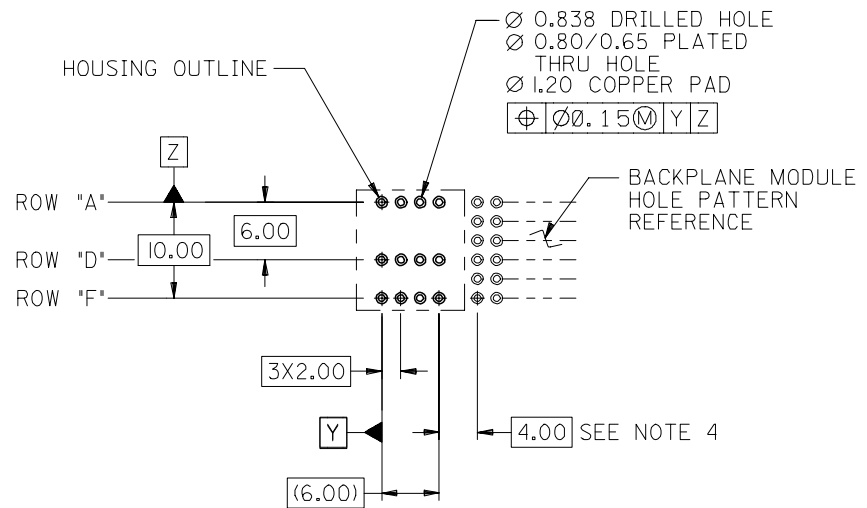
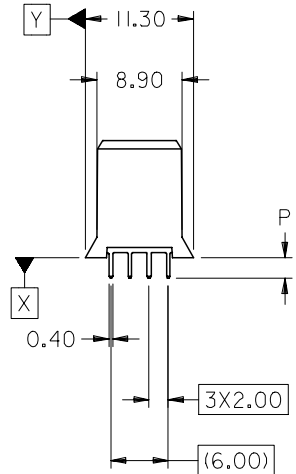
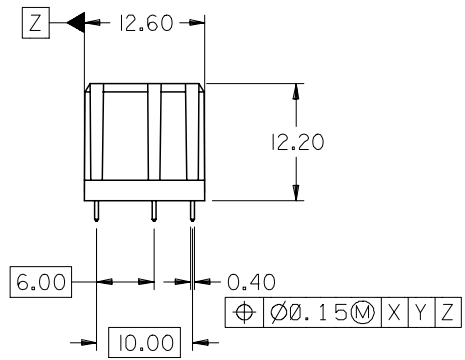
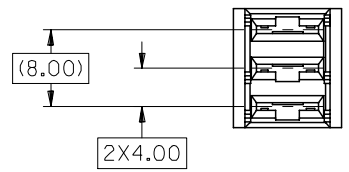
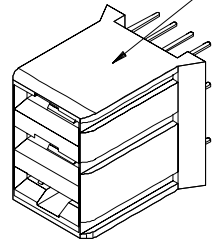
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MATERIAL NUMBER	DIM "P" ±0.25
73659-0001	2.00
73659-0002	2.50
73659-0003	3.00
73659-0004	3.50

DATE CODE AND PART NUMBER ON THIS SURFACE OR SURFACE OPPOSITE.

NOTES:

- MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
TERMINAL - BERYLLIUM COPPER
- FINISH:
0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
NICKEL (Ni) UNDERPLATE OVERALL.
- THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
- THIS DIMENSION MUST BE A MULTIPLE OF 4.00mm.
- DIMENSION ARE IN MILLIMETERS.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 1.57 MIN

MODIFY FINISH EC NO: UCP2007-2259 DRWN:MSI/BARRA 2007/03/13 CHKD:BBARKER 2007/03/21 APPR:SMILLER 2007/03/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0 ▽=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.10 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ±1/2°	MM ONLY	2:1	METRIC	
	DRAWN BY REED DATE 1996/12/10 CHECKED BY BINGHAM DATE 1996/12/10 APPROVED BY BIXLER DATE 1996/12/10	TITLE		SALES ASSY HDM BACKPLANE POWER MODULE WITH SOLDER TAILS		
	MATERIAL NO. SEE TABLE DOCUMENT NO. SDA-73659-000* SHEET NO. 1 OF 1	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX INCORPORATED		